LEOCO CORPORATION PRODUCTION SPECIFICATION No. S-96-5700 REV 3

5700 F Series and 5700 M Series Connector System

TEST METHOD & CONDITION

测试方法与条件

This product specification contains the test method, the general performance and requirements For wire to wire power connector with 5700 F series receptacle connector and mates with 5714 crimp terminal,5700 M series plug connector mates with 5713 crimp terminal.

1. Construction and dimensions shall be in accordance with the referenced drawings. 产品结构和尺寸依据所提供的产品图面.

2. Characteristics 特性:

ITEM

Current rating 额定电流: 3A AC Voltage rating 额定电压: 250V DC

Temperature rating 额定温度: -25℃ ~ +85℃

Applicable wire 适用线材: conductor construction size #24 ~ #28

3. Electrical performance 电气特性: DESCRIPTION

内容

3-1	Contact Resistance 接触阻抗	It should be tested in accordance with method EIA-364-23	Initial:20 m Ω max. After environmental Test:40 m Ω max.								
3-2	Insulation Resistance 绝缘阻抗	It should be tested in accordance with Method EIA-364-21	Initial :1000 M Ω min. After humidity and thermal shock test: 500M Ω min.								
3-3	Dielectric Withstanding Voltage 耐电压	Unmated connectors shall be tested in Accordance with method EIA-364-20 when the AC 1000 V rms for one minute applied between adjacent contacts.	No evidence of break- Down and flashover								
4. Mechanical Performance 机械特性:											
ITEM	DESCRIPTION 内容	TEST METHOD & CONDITION 测试方法与条件	REQUIREMENT 需 求								
4-1	Crimp Tensile Strength 铆合张力强度	Pulling load shall be applied between Correctly crimped contact and wire at a constant speed. Pulling speed: 25 mm / minute.	AWG #24: 2.5kgf min AWG #26: 1.5 kgf min. AWG #28: 1.0 kgf min.								
4-2	Contact Insertion Force 接触插入力	The force required to insert a contact into a housing. Inserting speed: 25 mm / minute.	1.05kgf max.								
4-3	Contact removal Force 接触拨出力	Crimped contact mounted in a housing shall be pulled in an alignment at a constant speed of 25 mm / minute.	1.5Kgf min.								
4-4	Insertion Force 插入力	Housing with contact mating plug at a constant speed of 25 mm / minute.	See parameters 6								
4-5	Withdrawal Force 拨出力	Housing with contact mating header, Pull out from header at speed 25 mm / minute.	See parameters 6								
4-6	Durability 耐久性	It should be tested in accordance with method EIA-364-09. Connector shall be subjected to 100 cycles of insertion and withdrawal	No defects. Contact resistance shall be $20m\Omega$ max								

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REQUIREMENT

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LEOCO CORPORATION			PRODUC	CTION S	SPECIFICAT	ΓΙΟΝ	No. S	-96-5700	REV	3			
ITEM DESCRIPTION 内容			TEST METHOD & CONDITION 测试方法与条件				REQUIREMENT 需 求						
	4-7		ration J测试	The connector mated PCB shall be vibrated in accordance with method EIA-364-28. There shall be no current discontinuity longer than 1 microsecond during the test. Frequency:10-55-10 Hz/min. Amplitude:1.52mm Period:2 hours for each direction.				No evidence of loosening of parts or electric discontinuity. Contact resistance less than twice of initial.					
5. Environmental Performance 环境特性:													
Item		DE:	SCRIPTION 内容	TEST METHOD & CONDITION 测试方法与条件				REQUIREMENT 需 求					
	5-1 Humidity 耐湿性			The unmated connector shall be tested in accordance with method EIA6364-31. Temperature: 40±2 °C Humidity: 90 ~ 95 % (RH) Period: 96 hours.				No damage. Contact resistance less Than twice of initial. Insulation resistance: to paragraph. 3-2. Dielectric withstand ing voltage: to paragraph 3-3					
5-2 Thermal sho 冷热冲击			one cycle consists of: -25°C for 30 minutes. +85°C for 30 minutes. Times of cycle:25 cycles.				No damage. Contact resistance less Than twice of initial. Insulation resistance: to paragraph. 3-2. Dielectric withstand ing voltage: to paragraph 3-3						
5-3		Salt Spray 盐雾试验		Connector shall be tested in accordance with method EIA-364-26 .Temperature :35±2 °C Density:5% in weight. Period:16 hours				No damage. Contact resistance less than twice of initial					
5-4		Solderability 着锡性		Connector termination ends shall be checked for solderability in accordance with method EIA-364-252. Solder temperature: 245±5°C Immersion period:5±0.5 sec.			No damage. Minimum:95% of immersed area.						
5-5		Resistance to soldering heat 附着耐热性		Specimen shall be mounted on PCB. Solder temperature: 260±5°C Immersion period:5±0.5 sec.			B.	No damage and deformation.					
6.Mating force and unmating								Unit :Kgf					
	Numbe circuits	r of Mating Force		Unmating Nu Force(min.) circ		Number of circuits		ng Force Unmating Force(min.)					
	Cinal		Initial max. 0.8	Initial 0.3	30th 0.1					30t 0.6			
	Single 2	C	1.60	0.60	0.1	7		5.6	2.1				
3 4		2.4		0.80	0.2	8 9		6.4		2.1 0.7 2.4 0.8			
				1.2	0.3			7.2	2.7 0.				
	5		4.0	1.5	0.5	10		3.0	3.0	1.0			
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